ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC. Bannockl	burn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	vithin the manufactu level materials for w	rer listed	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.
				Form Type Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and				ials and N	Ifg Informa	tion		
Supplier Information													
Company name* Com		Company un	Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-12			
Contact Name Title - Contac			act			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			resentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product En			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version Manufacturing Site			Weight*	UOM	Unit Type	
	MDB10	MDB10S S/P_BR M		BR MDIP PN 1A 1000V		2025-05-12		TSCBE		120.0		mg	Each
Aanufacturing Proccess Informa	ation												
Terminal Plating / Grid Array M	Iaterial 7	Ferminal Base A	Alloy J-STD-020 MSL Rati		L Rating	Peak Proce	k Process Body Temperature		re Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU Allo		CU Alloy	1			260 C		30	seconds 3				
omments													
vel 1 - maximum time at peak temperat	ture during so	Idering is 10-3	0 seconds										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.8	mg	Supplier	Silicon (Si)	7440-21-3		4.32	mg
			В	Nickel (Ni)	7440-02-0		0.0312	mg
			Supplier	Gold (Au)	7440-57-5		0.0072	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.4416	mg
Die Attach Solder	3.6	mg	Supplier	Silver (Ag)	7440-22-4		0.09	mg
			А	Lead (Pb)	7439-92-1	7a	3.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.18	mg
Lead Frame	48.6	mg	Supplier	Iron (Fe)	7439-89-6		0.0486	mg
			Supplier	Copper (Cu)	7440-50-8		48.5368	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0146	mg
Mold Compound-Black	61.2	mg		Metal Hydroxide	proprietary data		3.06	mg
			Supplier	Carbon Black (C)	1333-86-4		0.612	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		45.9	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		6.12	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		5.508	mg
Plating	1.8	mg	Supplier	Tin (Sn)	7440-31-5		1.8	mg